

Electronic Patent Application Fee Transmittal

Application Number:	10550153			
Filing Date:	20-Sep-2005			
Title of Invention:	Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product			
First Named Inventor/Applicant Name:	Toshikazu Okubo			
Filer:	Song Zhu			
Attorney Docket Number:	38915.00045			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Petition fee- 37 CFR 1.17(f) (Group I)	1462	1	400	400
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				400